

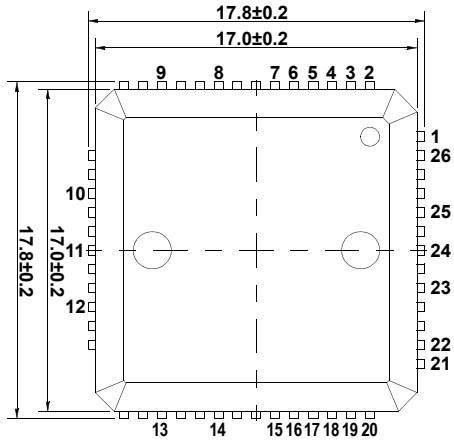
Plastic Packages for Integrated Circuits

Package Outline Drawing

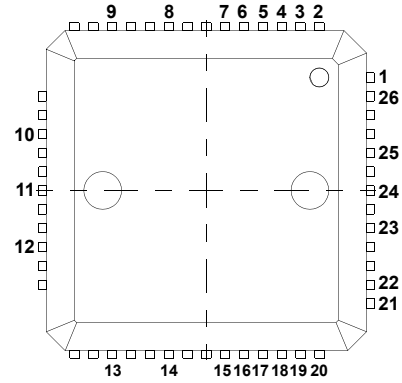
L26.17x17

26 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN)

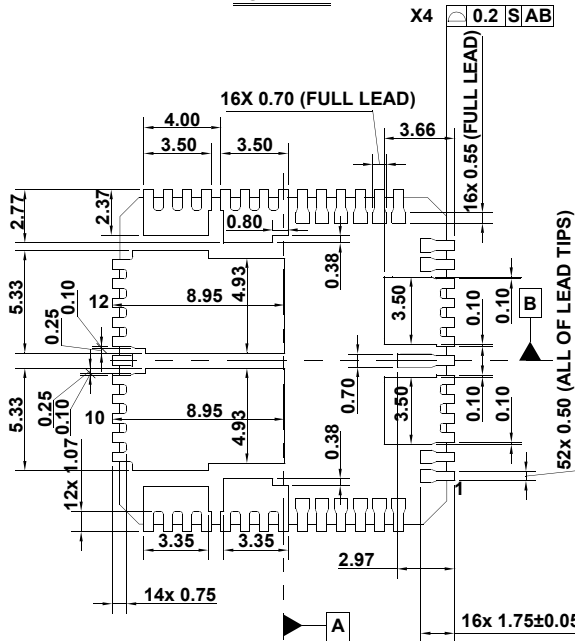
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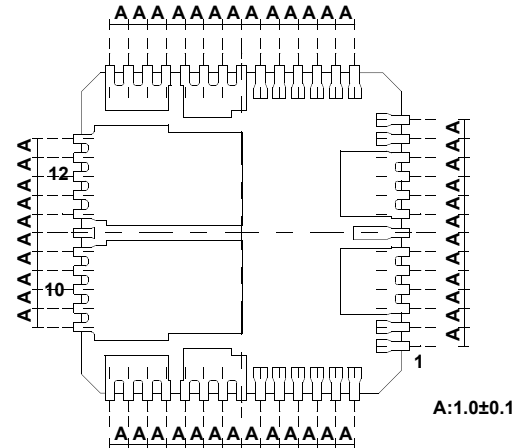
TOP VIEW



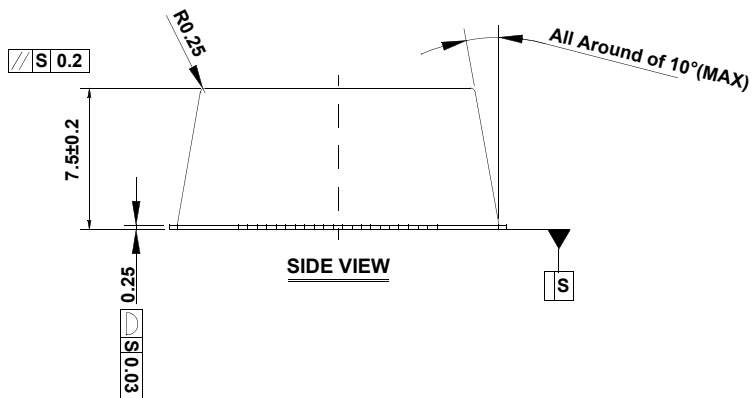
PIN NO. DEFINITION (TOP VIEW)



BOTTOM VIEW

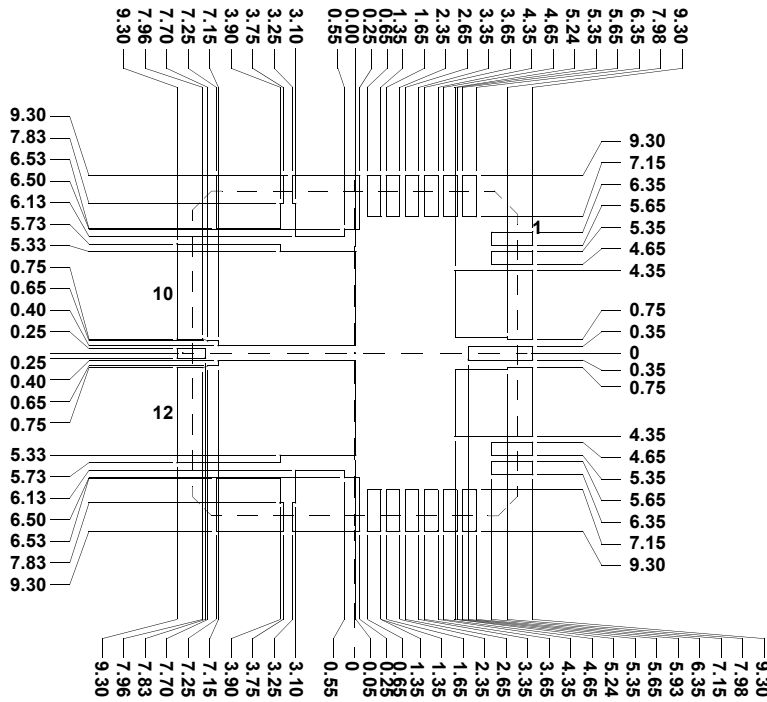


PIN-TO-PIN DISTANCE (BOTTOM VIEW)

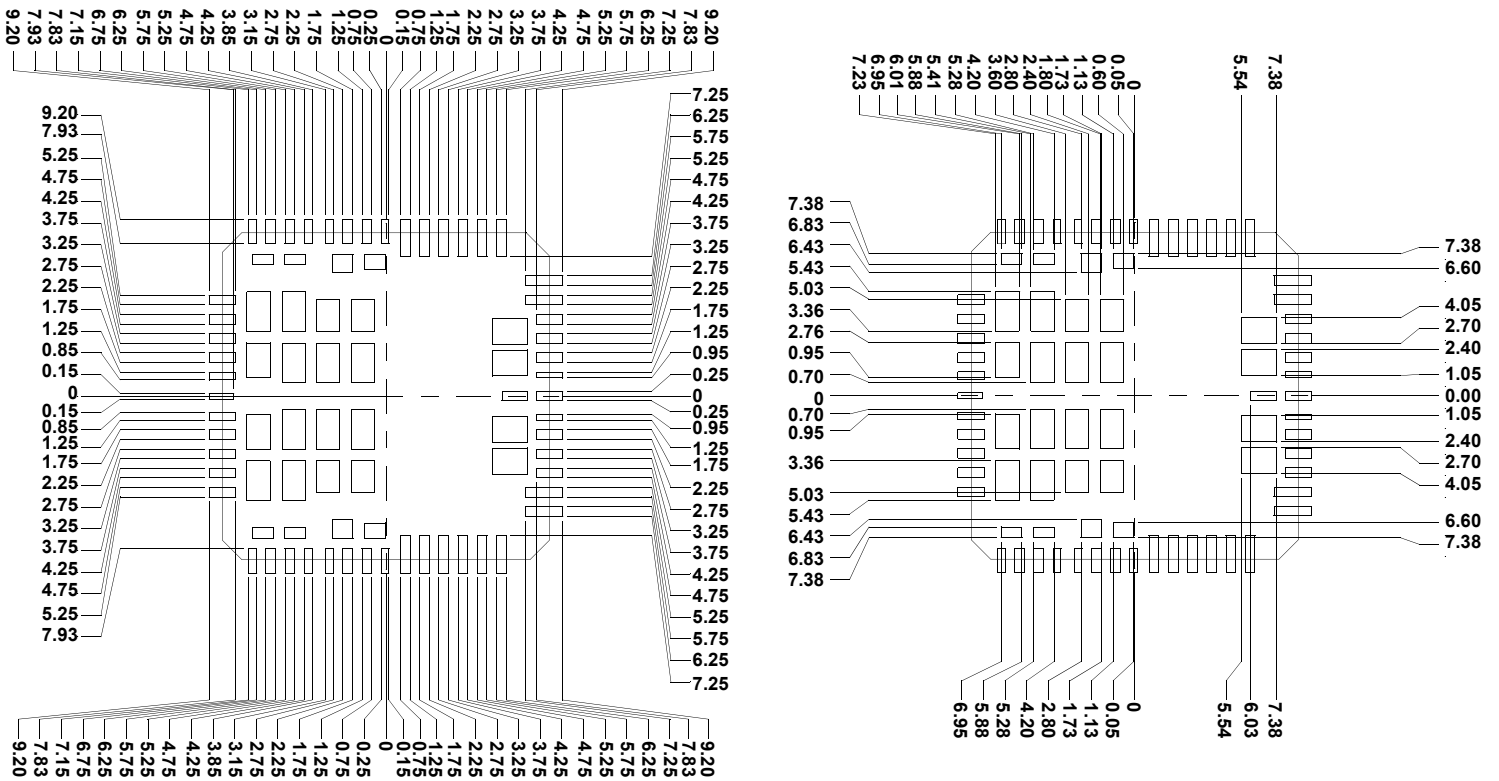


SIDE VIEW

Plastic Packages for Integrated Circuits



TYPICAL RECOMMENDED LAND PATTERN (TOP VIEW)



SOLDER STENCIL PATTERN WITH SQUARE PADS 1 OF 2 (TOP VIEW)

SOLDER STENCIL PATTERN WITH SQUARE PADS 2 OF 2 (TOP VIEW)